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PRESS RELEASE

MacDermid Alpha Introduces ALPHA® OM-377 Solder Paste for Reliable Ultra-Fine Feature Printing at Production Scale

(Waterbury, CT, USA) – June 04, 2026. MacDermid Alpha Electronics Solutions, a leading supplier of integrated materials and chemistry solutions for the electronics industry, announced the launch of ALPHA® OM-377, a no-clean solder paste engineered for ultra-fine feature printing in advanced electronics assemblies.

The formulation is designed to support long-term electrochemical reliability while helping manufacturers reduce processing and print defects in high-volume production environments.

As electronics continue to miniaturize, component geometries are shrinking while assembly tolerances become increasingly tight across mobile, wearable, and other miniaturized, high-functioning applications. Manufacturers continue to advance yield and process control as ultra-fine geometries scale into high-volume production. These demands require materials capable of delivering reliable defect mitigation at ultra-fine feature sizes.

ALPHA OM-377 is engineered to address these challenges through:

- **Ultra-fine feature printing** down to 008004 component sizes
- **Consistent solder paste transfer efficiency** across fine-pitch designs
- **Superior electrochemical performance** to support long-term operational reliability
- **Improved first-pass yield** through reduced Head-in-Pillow (HiP) and Non-Wet Open (NWO) defects
- **Reliable wetting performance** on brass and nickel surfaces

These capabilities enable manufacturers to maintain high throughput, improve process control, and confidently scale high-density, low-standoff assemblies using fine-pitch components.

ALPHA OM-377 delivers stable performance across both printing and reflow, supporting consistent assembly outcomes in demanding production environments. The advanced chemistry supports no-clean processing with low post-reflow residue suited for dense designs, while its halogen-free composition aligns with current environmental and compliance requirements for high-volume manufacturing.

“Ultra-fine feature designs require consistent printing and reflow performance at production scale,” said Sam Foo, Regional Product Manager, Solder Paste. “ALPHA OM-377 is designed to help manufacturers protect yield, maintain process stability, and support reliable assembly performance in high-density applications.”

As consumer electronics continue to miniaturize while integrating greater functionality, materials capable of supporting scalable ultra-fine feature assembly will remain critical to next-generation electronics manufacturing.

To learn more about ALPHA OM-377 and its capabilities in ultra-fine feature assembly, visit macdermidalpha.com.

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MacDermid Alpha Electronics Solutions, a business unit of Element Solutions Inc, is a global leader in high-performance specialty chemicals, materials, and process technologies for every stage of the electronics manufacturing process. With expertise spanning circuitry formation, wafer-level packaging, circuit board assembly, semiconductor assembly, and film and smart surfaces, MacDermid Alpha delivers advanced, sustainable, and integrated solutions that drive innovation and reliability across the electronics supply chain. Operating worldwide and backed by more than a century of innovation, the organization supports a broad range of industries including automotive, consumer electronics, data infrastructure, high-performance computing, and telecommunications enabling next-generation electronics.

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